SDAS083C - APRIL 1982 - REVISED MARCH 2002

- Eight Latches in a Single Package
- 3-State Bus-Driving True Outputs

• Full Parallel Access for Loading

- Buffered Control Inputs
- pnp Inputs Reduce dc Loading on Data Lines

description

These octal transparent D-type latches feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

While the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is taken low, the Q outputs are latched at the logic levels set up at the D inputs.

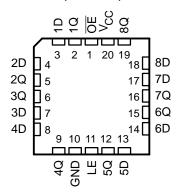
A buffered output-enable (\overline{OE}) input can be used to place the eight outputs in either a normal logic state (high or low) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines without interface or pullup components.

 $\overline{\text{OE}}$ does not affect internal operations of the latches. Old data can be retained or new data can be entered while the outputs are off.

SN54ALS373A, J OR W PACKAGE
SN54AS373 J PACKAGE
SN74ALS373A, SN74AS373 DW, N, OR NS PACKAGE
(TOP VIEW)

OE		U	20] v _{cc}
1Q	2		19] 8Q
1D	[] 3		18] 8D
2D	4		17] 7D
2Q	[5		16] 7Q
3Q	6		15] 6Q
3D	[7		14] 6D
4D	8]		13] 5D
4Q	[9		12] 5Q
GND	[10		11] LE

SN54ALS373A, SN54AS373...FK PACKAGE (TOP VIEW)





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



Copyright © 2002, Texas Instruments Incorporated On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

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TA	PAC	PACKAGE [†] ORDERABLE PART NUMBER		TOP-SIDE MARKING				
	PDIP – N	Tube	SN74ALS373AN	SN74ALS373AN				
	PDIP – N	Pdbe	SN74AS373N	SN74AS373N				
		Tube	SN74ALS373ADW	ALS373A				
0°C to 70°C	°C SOIC – DW	Tape and reel	SN74ALS373ADWR	ALSSTSA				
		Tube	SN74AS373DW	46272				
		Tape and reel	SN74AS373DWR	AS373				
	005 10	Topo and roal	SN74ALS373ANSR	ALS373A				
	SOP – NS	Tape and reel	SN74AS373NSR	74AS373				
	CDIP – J	Tube	SNJ54ALS373AJ	SNJ54ALS373AJ				
	CDIP – J	PdbP	SNJ54AS373J	SNJ54AS373J				
–55°C to 125°C	CFP – W	Tube	SNJ54ALS373AW	SNJ54ALS373AW				
		Taba	SNJ54ALS373AFK	SNJ54ALS373AFK				
	LCCC – FK	Tube	SNJ54AS373FK	SNJ54AS373FK				

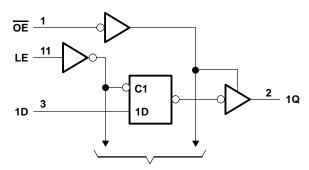
ORDERING INFORMATION

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE
(each latch)

	INPUTS	OUTPUT	
OE	LE	D	Q
L	Н	Н	Н
L	Н	L	L
L	L	Х	Q ₀
н	Х	Х	Z

logic diagram (positive logic)



To Seven Other Channels



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absolute maximum ratings over operating free-air temperature range (SN54ALS373A, SN74ALS373A) (unless otherwise noted)[†]

Supply voltage, V _{CC}	
Input voltage, V ₁	
Package thermal impedance, θ_{IA} (see Note 1): DW pack	
	e 69°C/W
NS packa	age 60°C/W
Storage temperature range, T _{stg}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions

		SN5	54ALS37	'3A	SN74ALS373A			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.7			0.8	V
ЮН	High-level output current			-1			-2.6	mA
IOL	Low-level output current			12			24	mA
Т _А	Operating free-air temperature	-55		125	0		70	°C

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

		SN54ALS373A MIN MAX		SN74AL	UNIT	
				MIN	MAX	UNIT
fclock	Clock frequency					MHz
tw	Pulse duration, LE high	12		10		ns
t _{su}	Setup time, data before LE \downarrow	10		10		ns
t _h	Hold time, data after LE \downarrow	7		7		ns



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TERTO	TEST CONDITIONS		4ALS37	'3A	SN7			
PARAMETER	TEST C	UNDITIONS	MIN	түр†	MAX	MIN	түр†	MAX	UNIT
VIK	V _{CC} = 4.5 V,	lj = -18 mA			-1.5			-1.5	V
	V _{CC} = 4.5 V to 5.5 V,	I _{OH} = -0.4 mA	V _{CC} –2			V _{CC} –2			
VOH	$\lambda = -45\lambda$	I _{OH} = -1 mA	2.4	3.3					V
	$V_{CC} = 4.5 V$	I _{OH} = -2.6 mA				2.4	3.2		
N/		I _{OL} = 12 mA		0.25	0.4		0.25	0.4	V
VOL	$V_{CC} = 4.5 V$	I _{OL} = 24 mA					0.35	0.5	v
lozh	V _{CC} = 5.5 V,	V _O = 2.7 V			20			20	μA
I _{OZL}	V _{CC} = 5.5 V,	V _O = 0.4 V			-20			-20	μA
lj	V _{CC} = 5.5 V,	V _I = 7 V			0.1			0.1	mA
Iн	V _{CC} = 5.5 V,	V _I = 2.7 V			20			20	μA
١ _{١L}	V _{CC} = 5.5 V,	V _I = 0.4 V			-0.1			-0.1	mA
IO‡	V _{CC} = 5.5 V,	V _O = 2.25 V	-20		-112	-30		-112	mA
		Outputs high		9	16		9	16	
ICC	$V_{CC} = 5.5 V$	Outputs low		16	25		16	25	mA
		Outputs disabled		17	27		17	27	

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[‡] The output conditions have been chosen to produce a current that closely approximates one-half of the true short-circuit output current, IOS.

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	то (оитрит)	Cl R1 R2	_ = 50 pl l = 500	2,	,	UNIT
		SN54AL		S373A	SN74ALS373A		
			MIN	MAX	MIN	MAX	
^t PLH	D		2	17	2	12	ns
^t PHL		Q	1	19	4	16	115
^t PLH		4	6	29	6	22	ns
^t PHL	LE	Any Q	1	27	7	23	115
^t PZH			6	22	1	18	
^t PZL	OE	Any Q	5	24	5	20	ns
^t PHZ	ŌĒ	Apy O	2	16	1	10	
^t PLZ	UE	Any Q	2	24	2	12	ns

§ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



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absolute maximum ratings over operating free-air temperature range (SN54AS373, SN74AS373) (unless otherwise noted)[†]

Supply voltage, V _{CC} Input voltage, V _I		
Voltage applied to any output in the high state of		
Package thermal impedance, θ_{JA} (see Note 1):	DW package	58°C/W
	N package	69°C/W
	NS package	60°C/W
Storage temperature range, T _{stg}	·	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 2: The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions

		SN54AS373 SN74AS373			/3	UNIT		
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.8			0.8	V
ЮН	High-level output current			-12			-15	mA
IOL	Low-level output current			32			48	mA
Т _А	Operating free-air temperature	-55		125	0		70	°C

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

		SN54A	S373	SN74A	UNIT	
		MIN	MAX	MIN	MAX	UNIT
fclock	Clock frequency					MHz
tw	Pulse duration, LE high	5.5*		4.5*		ns
t _{su}	Setup time, data before LE \downarrow	2*		2*		ns
t _h	Hold time, data after LE \downarrow	3*		3*		ns

* On products compliant to MIL-STD-883, Class B, this parameter is based on characterization data but is not production tested.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST CONDITIONS			154AS37	'3	SN	3	UNIT	
PARAMETER	TEST C	MIN	түр†	MAX	MIN	TYP†	MAX	UNIT	
VIK	V _{CC} = 4.5 V,	lı = –18 mA			-1.2			-1.2	V
	V _{CC} = 4.5 V to 5.5 V,	$I_{OH} = -2 \text{ mA}$	V _{CC} –2			V _{CC} –2			
VOH		I _{OH} = -12 mA	2.4	3.2					V
	$V_{CC} = 4.5 V$	I _{OH} = -15 mA				2.4	3.3		
Ve	$\lambda = 45 \lambda$	I _{OL} = 32 mA		0.27	0.5				V
VOL	$V_{CC} = 4.5 V$	I _{OL} = 48 mA					0.32	0.5	v
IOZH	V _{CC} = 5.5 V,	V _O = 2.7 V			50			50	μA
IOZL	$V_{CC} = 5.5 V,$	V _O = 0.4 V			-50			-50	μA
lj	$V_{CC} = 5.5 V,$	$V_{I} = 7 V$			0.1			0.1	mA
Ιн	V _{CC} = 5.5 V,	VI = 2.7 V			20			20	μA
١ _{١L}	V _{CC} = 5.5 V,	VI = 0.4 V		-0.02	-0.5		-0.02	-0.5	mA
10‡	V _{CC} = 5.5 V,	V _O = 2.25 V	-30		-112	-30		-112	mA
		Outputs high		55	90		55	90	
ICC	$V_{CC} = 5.5 V$	Outputs low		55	85		55	85	mA
		Outputs disabled		65	100		65	100	

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[‡] The output conditions have been chosen to produce a current that closely approximates one-half of the true short-circuit output current, IOS.

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	Ci R ² R2	CC = 4.5 L = 50 pF 1 = 500 Ω 2 = 500 Ω A = MIN t	<u>2,</u> 2,	3	UNIT
			SN54A	S373	SN74AS373		
			MIN	MAX	MIN	MAX	
^t PLH	D		3	9	3.5	6	ns
^t PHL	U	Q	3	8	3.5	6	115
^t PLH	LE	10	6.5	14.5	6.5	11.5	20
^t PHL	LC	Any Q	5	9	5	7.5	ns
^t PZH		10	2	7.5	2	6.5	
^t PZL	OE	Any Q	4.5	10.5	4.5	9.5	ns
^t PHZ	ŌĒ	Am/ 0	3	10	3	6.5	
^t PLZ	UE	Any Q	3	8	3	7	ns

§ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

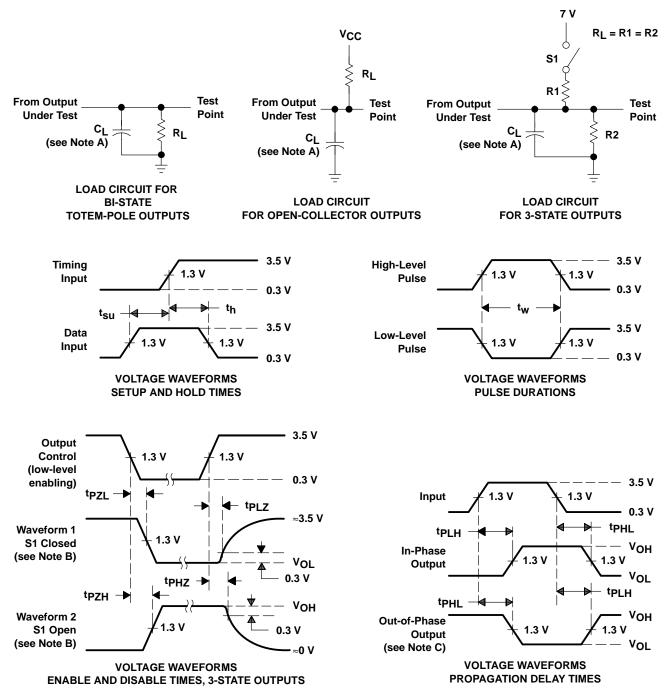


SN54ALS373A, SN54AS373, SN74ALS373A, SN74AS373 OCTAL TRANSPARENT D-TYPE LATCHES

WITH 3-STATE OUTPUTS

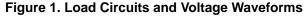
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PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: PRR \leq 1 MHz, t_r = t_f = 2 ns, duty cycle = 50%.
- D. All input pulses have the following characteristics. FRR ≤ 1 with z_i , $t_i = t_i = 2$ hs, duty cycle =
- E. The outputs are measured one at a time with one transition per measurement.







10-Jun-2014

PACKAGING INFORMATION

Orderable Device		Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
83020012A	(1) ACTIVE	LCCC	FK	20	1	(2) TBD	(6) POST-PLATE	(3) N / A for Pkg Type	-55 to 125	(4/5) 83020012A SNJ54ALS 373AFK	Samples
8302001RA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8302001RA SNJ54ALS373AJ	Samples
8302001SA	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8302001SA SNJ54ALS373AW	Samples
JM38510/37203B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 37203B2A	Samples
JM38510/37203BRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 37203BRA	Samples
M38510/37203B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 37203B2A	Samples
M38510/37203BRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 37203BRA	Samples
SN54ALS373AJ	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54ALS373AJ	Samples
SN54AS373J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54AS373J	Samples
SN74ALS373ADBLE	OBSOLETE	SSOP	DB	20		TBD	Call TI	Call TI	0 to 70		
SN74ALS373ADBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	G373A	Samples
SN74ALS373ADW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS373A	Samples
SN74ALS373ADWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS373A	Samples
SN74ALS373ADWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS373A	Samples
SN74ALS373ADWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS373A	Samples
SN74ALS373AN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS373AN	Samples
SN74ALS373AN3	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI	0 to 70		
SN74ALS373ANSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS373A	Samples



PACKAGE OPTION ADDENDUM

10-Jun-2014

Orderable Device	Status	Package Type		Pins		Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
SN74ALS373ANSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS373A	Samples
SN74AS373DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	AS373	Samples
SN74AS373DWR	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	0 to 70	AS373	
SN74AS373DWRE4	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	0 to 70		
SN74AS373DWRG4	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI	0 to 70		
SN74AS373N	ACTIVE	PDIP	Ν	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74AS373N	Samples
SN74AS373N3	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI	0 to 70		
SN74AS373NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74AS373	Samples
SNJ54ALS373AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	83020012A SNJ54ALS 373AFK	Samples
SNJ54ALS373AJ	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8302001RA SNJ54ALS373AJ	Samples
SNJ54ALS373AW	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8302001SA SNJ54ALS373AW	Samples
SNJ54AS373FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54AS 373FK	Samples
SNJ54AS373J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54AS373J	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between

the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.



PACKAGE OPTION ADDENDUM

10-Jun-2014

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54ALS373A, SN54AS373, SN74ALS373A, SN74AS373 :

- Catalog: SN74ALS373A, SN74AS373
- Military: SN54ALS373A, SN54AS373

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

www.ti.com

Pin1

Quadrant

Q1

Q1

Q1

Q1

P1

(mm)

12.0

12.0

12.0

12.0

w

(mm)

16.0

24.0

24.0

24.0

TAPE AND REEL INFORMATION

REEL DIMENSIONS

TEXAS INSTRUMENTS





SO

SO

NS

NS

TAPE AND REEL INFORMATION

SN74ALS373ANSR

SN74AS373NSR

TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

All dimensions are nominal									
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)
SN74ALS373ADBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5
SN74ALS373ADWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7

20

20

2000

2000

330.0

330.0

24.4

24.4

8.2

8.2

13.0

13.0

2.5

2.5

TEXAS INSTRUMENTS

www.ti.com

PACKAGE MATERIALS INFORMATION

17-Aug-2012



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS373ADBR	SSOP	DB	20	2000	367.0	367.0	38.0
SN74ALS373ADWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74ALS373ANSR	SO	NS	20	2000	367.0	367.0	45.0
SN74AS373NSR	SO	NS	20	2000	367.0	367.0	45.0

J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- NOTES: A. All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice. В.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 D. Index point is provided on cap for terminal identification only.
 E. Falls within Mil-Std 1835 GDFP2-F20



LEADLESS CERAMIC CHIP CARRIER

FK (S-CQCC-N**) 28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013 variation AC.



LAND PATTERN DATA



NOTES:

A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Refer to IPC7351 for alternate board design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

MSSO002E - JANUARY 1995 - REVISED DECEMBER 2001

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-150



MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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